

FEATURES

ESD protection	for high speed d	ata lines to IEC610	000-4-2
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| ESD contact discharge typical 8KV, max 15KV

| ESD air discharge typical 15KV, max 25KV

Surface mount

| Extremely low capacitance

I Very low leakage current

Fast response time

| Bi-directional ESD protection

Lead free solder termination

The best ESD protection for high frequency, low voltage applications





APPLICATIONS

USB3.0, Firewire, DVI, HDMI, S-ATA, Thunderbolt

| Mobile HDMI Link, MDDI, MIPI, SWP/NFC

APPROVALS

	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003

MECHANICAL DATA

| Case: 0402 (plastic package)

| Molding Compound Flammability Rating:UL 94 V-0



ABSOLUTE MAXIMUM RATINGS

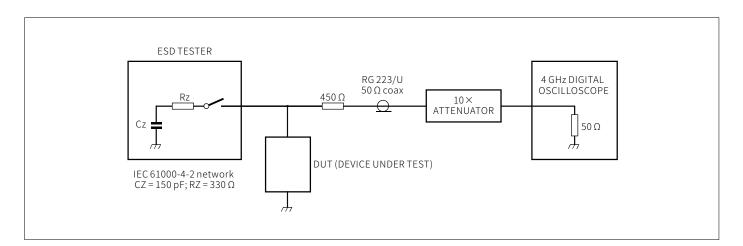
Symbol	Parameter	Value	Unit
-	Maximum Contact discharge voltage Per IEC61000-4-2	15KV	V
-	Maximum Air discharge voltage Per IEC61000-4-2	25KV	V
T _{OPER}	Maximum Operating temperature	-40 to +90	°C
T _{STG}	Maximum Storage temperature	-55 to +125	°C

ELECTRICAL CHARACTERISTICS (T_A=25°C)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V_R	Rated Voltage	-	-	-	5	V
V _T	Trigger Voltage	IEC61000-4-28KV contact discharge	-	300	-	V
V _c	Clamping Voltage	IEC61000-4-28KV contact discharge	-	35	-	V
I	Leakage Current	DC 5V shall be applied on component	-	-	0.10	μΑ
C _P	Capacitance	$V_R = 0V, f = 1MHz$	-	0.05	-	pF

Note:

ESD CLAMPING TEST

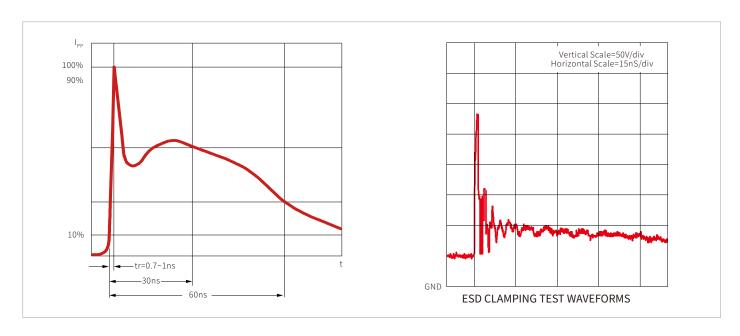


^{1.} Trigger and clamping voltage are measured per IEC 61000-4-2, 8 KV contact discharge method.

^{2、}After reliability tests such as high temp storage, temp cycles, continuous ESD strike etc, the maximum leakage current is less than 10uA.

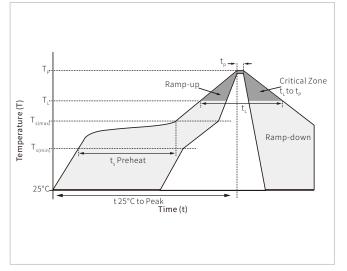


CHARACTERISTIC CURVES



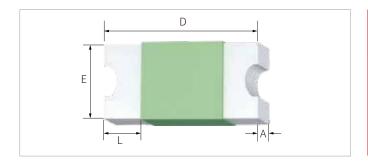
SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly	
	Temperature Max (T _{s(min)})	150°C	
Pre Heat	Temperature Max (T _{s(max)})	200°C	
	Time (min to max) (t _s)	60 – 180 secs	
Average ran	Average ramp up rate (Liquidus Temp (T_L) to peak		
	T _{s(max)} to T _L - Ramp-up Rate		
Reflow	Temperature (T _L) (Liquidus)	217°C	
Kellow	Time (min to max) (t_L)	60 – 150 seconds	
Peak Temperature (T _P)		260°C	
Time within 5°C of actual peak Temperature (t _o)		20 – 40 seconds	
Ramp-down Rate		6°C/second max	
Time 25°C to peak Temperature (T _P)		8 minutes max.	
Do not exceed		260°C	



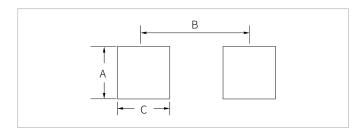


PACKAGE INFORMATION



Ref.	Dimension				
i.c.i.	Min.	Тур.	Max.	Unit	
D	0.90	1.05	1.20		
Е	0.45	0.55	0.65	mm	
L	0.15	0.25	0.35		
А	0.25	0.35	0.45		

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Dimension	Unit
А	0.50	
В	0.90	mm
С	0.65	

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
SPE0402B5.0	0402	10000PCS	7"



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